- Single-Rail Outputs on 'LS399
- Selects One of Two 4-Bit Data Sources and Stores Data Synchronously with System Clock
- Applications:

Dual Source for Operands and Constants in Arithmetic Processor; Can Release Processor Register Files for Acquiring New Data

Implement Separate Registers Capable of Parallel Exchange of Contents Yet Retain External Load Capability

Universal Type Register for Implementing Various Shift Patterns: Even Has Compound Left-Right Capabilities

#### description

This monolithic quadruple two-input multiplexer with storage provides essentially the equivalent functional capabilities of two separate MSI functions (SN54LS157/SN74LS157 and SN54LS175/SN74LS175) in a single 16-pin package.

When the word-select input is low, word 1 (A1, B1, C1, D1) is applied to the flip-flops. A high input to word select will cause the selection of word 2 (A2, B2, C2, D2). The selected word is clocked to the output terminals on the positive-going edge of the clock pulse.

Typical power dissipation is 37 milliwatts. The SN54LS399 is characterized for operation over the full military range of  $-55\,^{\circ}\text{C}$  to  $125\,^{\circ}\text{C}$ . The SN74LS399 is characterized for operation from  $0\,^{\circ}\text{C}$  to  $70\,^{\circ}\text{C}$ .

**FUNCTION TABLE** 

	INPL	JTS	OUTPUTS							
ł.	VORD ELECT	CLOCK	QA	αB	σc	$\sigma_{D}$				
Г	L	1	a1	b1	c1	d1				
	н	1	a2	b2	c2	d2				
	X	L	Q <sub>A0</sub>	$\alpha_{\text{B0}}$	$\sigma_{\text{C0}}$	$\sigma_{D0}$				

SN54LS399 ... J OR W PACKAGE SN74LS399 ... D OR N PACKAGE (TOP VIEW)

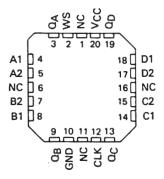
WS 1 1 16 VCC
QA 2 15 QD
A1 3 14 D1
A2 4 13 D2
B2 5 12 C2
B1 6 11 C1

GND □8

SN54LS399 . . . FK PACKAGE (TOP VIEW)

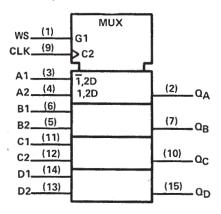
10 Q QC

9 CLK



NC - No internal connection

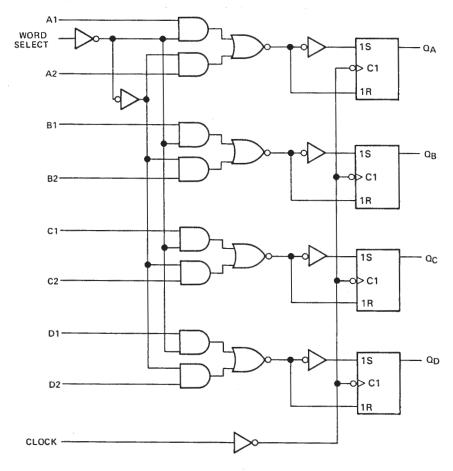
# logic symbol†



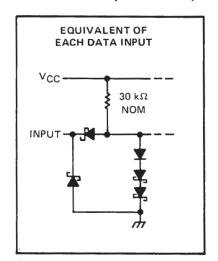
<sup>&</sup>lt;sup>†</sup>This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

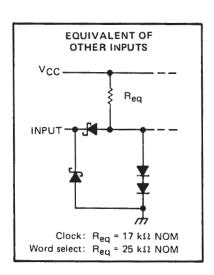
Pin numbers shown are for D, J, N, and W packages.

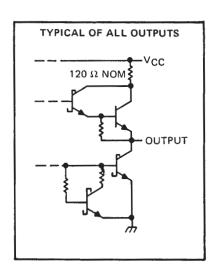
# logic diagram (positive logic)



# schematics of inputs and outputs







SDLS174 - OCTOBER 1976 - REVISED MARCH 1988

## absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, VCC (see Note 1)	. 7 V
Input voltage	. 7 V
Operating free-air temperature range: SN54LS399	25°C
SN74LS399 0°C to	70°C
Storage temperature range65 °C to 1	50°C

NOTE 1: Voltage values are with respect to network ground terminals.

### recommended operating conditions

		SN54LS399			,			
· · · · · · · · · · · · · · · · · · ·		MIN	NOM	MAX	MIN	NOM	MAX	UNIT
Supply voltage, V <sub>CC</sub>		4.5	5	5.5	4.75	5	5.25	٧
High-level output current, IOH				-400			-400	μА
Low-level output current, IOL			4			8	mA	
Width of clock pulse, high or low level, tw	Nidth of clock pulse, high or low level, t <sub>W</sub>							ns
Setup time, t <sub>su</sub>	Data	25			25			ns
octop time, t <sub>su</sub>	Word select	45			45			
Hold time, th	Data	0			0			
Tiona time, th	Word select	0			0			ns
Operating free-air temperature, TA		-55		125	0		70	°c

# electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	PARAMETER	7.50	SN54LS399			SN74LS399					
	FANAIVIETEN	1 63	TEST CONDITIONS†				MAX	MIN	ТҮР‡	MAX	UNIT
VIH	High-level input voltage				2			2			V
VIL	Low-level input voltage						0.7			0.8	V
VIK	Input clamp voltage	V <sub>CC</sub> = MIN,	I <sub>I</sub> = -18 mA				-1.5			-1.5	V
Vон	High-level output voltage	V <sub>CC</sub> = MIN, V <sub>IL</sub> = V <sub>IL</sub> max	V <sub>IH</sub> = 2 V, I <sub>OH</sub> = -400 μA		2.5	3.4		2.7	3.4		V
VOL	Low-level output voltage	V <sub>CC</sub> = MIN, V <sub>IL</sub> = V <sub>IL</sub> max	V <sub>IH</sub> = 2 V,	I <sub>OL</sub> = 4 mA		0.25	0.4		0.25 0.35	0.4	V
'i <sub>1</sub>	Input current at maximum input voltage	V <sub>CC</sub> = MAX,	V <sub>1</sub> = 7 V				0.1			0.1	mA
ЧΗ	High-level input current	V <sub>CC</sub> = MAX,	V <sub>I</sub> = 2.7 V				20			20	μА
ΠL	Low-level input current	V <sub>CC</sub> = MAX,	V <sub>I</sub> = 0.4 V				-0.4			-0.4	mA
los	Short-circuit output current §	V <sub>CC</sub> = MAX			-20		-100	-20		-100	mA
1CC	Supply current	V <sub>CC</sub> = MAX,	See Note 2			7.3	13		7.3	13	mA

<sup>&</sup>lt;sup>†</sup> For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

## switching characteristics, VCC = 5 V, TA = 25°C

	PARAMETER	TEST CON	IDITIONS	MIN	TYP	MAX	UNIT
tPLH	Propagation delay time, low-to-high-level output	C <sub>L</sub> = 15 pF,	$R_L = 2 k\Omega$ ,		18	27	
tPHL	Propagation delay time, high-to-low-level output	See Note 3			21	32	ns

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.



<sup>‡</sup>All typical values are at  $V_{CC} = 5 \text{ V}$ ,  $T_A = 25^{\circ}\text{C}$ .

<sup>§</sup> Not more than one output should be shorted at a time, duration of the short-circuit should not exceed one second .

NOTE 2: With all outputs open and all inputs except clock low, ICC is measured after applying a momentary 4.5 V, followed by ground, to the clock input.





24-Aug-2018

#### PACKAGING INFORMATION

Orderable Device	Status	Package Type	_		Package	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking	Samples
	(1)		Drawing		Qty	(2)	(6)	(3)		(4/5)	
8415401EA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	8415401EA SNJ54LS399J	Samples
SN54LS399J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	SN54LS399J	Samples
SN54LS399J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	SN54LS399J	Samples
SN74LS399N	ACTIVE	PDIP	N	16	25	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74LS399N	Samples
SN74LS399N	ACTIVE	PDIP	N	16	25	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74LS399N	Sample
SNJ54LS399J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	8415401EA SNJ54LS399J	Samples
SNJ54LS399J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	8415401EA SNJ54LS399J	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

**Green:** TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

<sup>(3)</sup> MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

<sup>(4)</sup> There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

<sup>(5)</sup> Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.



# PACKAGE OPTION ADDENDUM

24-Aug-2018

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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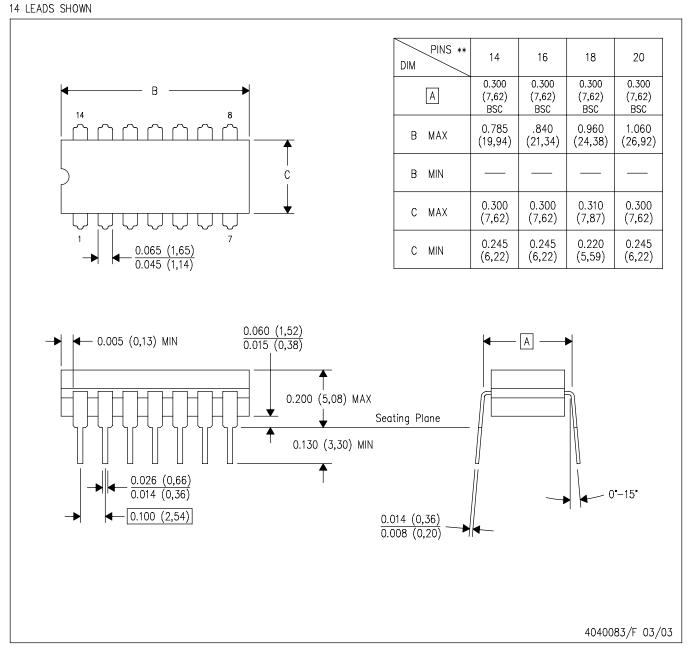
#### OTHER QUALIFIED VERSIONS OF SN54LS399, SN74LS399:

Catalog: SN74LS399

Military: SN54LS399

NOTE: Qualified Version Definitions:

- Catalog TI's standard catalog product
- Military QML certified for Military and Defense Applications



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

# N (R-PDIP-T\*\*)

# PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



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